

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,878,206 B2
APPLICATION NO. : 10/016300
DATED : April 12, 2005
INVENTOR(S) : Tzu et al.

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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page should be deleted and substitute therefore the attached title page.

Drawings:

Delete drawing sheets 1-2, and substitute therefore the drawing sheets, consisting of Figs. 1-2, as shown on the attached pages.

Col. 5, line 59, insert a space (" ") after "20g."

Signed and Sealed this

Seventeenth Day of October, 2006



JON W. DUDAS
Director of the United States Patent and Trademark Office

(12) United States Patent
Tzu et al.(10) Patent No.: US 6,878,206 B2
(45) Date of Patent: Apr. 12, 2005

(54) LID ASSEMBLY FOR A PROCESSING SYSTEM TO FACILITATE SEQUENTIAL DEPOSITION TECHNIQUES

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(73) Assignee: Applied Materials, Inc., Santa Clara, CA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 145 days.

(21) Appl. No.: 10/016,300

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(65) Prior Publication Data

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Related U.S. Application Data

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(52) U.S. Cl. 118/715; 118/728; 156/345.29; 156/345.33

(58) Field of Search 118/715, 728, 118/50; 156/345.29, 345.33, 345.34, 345.35, 345.36, 345.26, 345.51; 137/262, 263, 264, 454.2, 560, 561 R, 561 A, 571, 572, 573, 574, 575, 576, 590, 594-596, 599.01, 599.05-599.07, 602; 141/285, 286, 37, 44-47, 54, 301-302, 367

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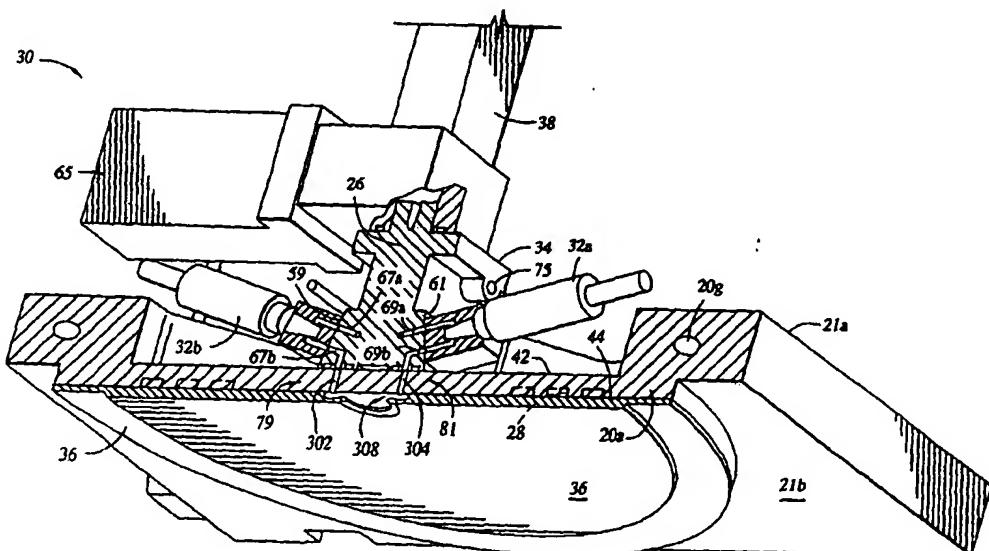
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(57) ABSTRACT

A lid assembly for a semiconductor processing system is provided. The lid assembly generally includes a lid having a gas manifold mounted on a first side and a baffle plate mounted on a second side. The gas manifold is configured to deliver a plurality of gases to a plenum defined between the baffle plate and the lid. The gases are mixed within a recess formed in the baffle plate before exiting into the processing system through a singular passage.

23 Claims, 8 Drawing Sheets



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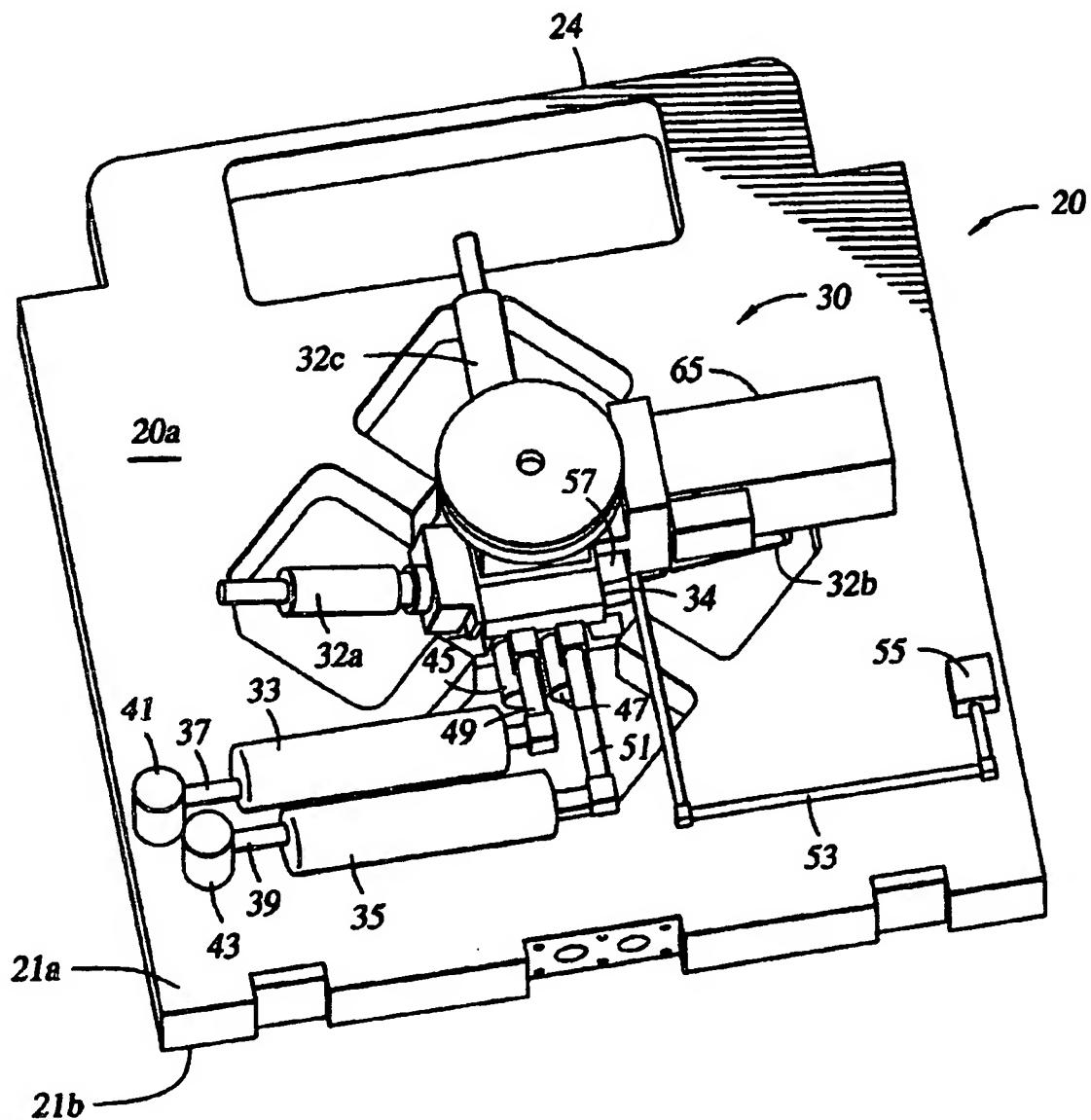


Fig. 2

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